

### ■ Absolute Maximum Rating

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	$I_F$	80	mA
Peak Forward Current*	$I_{FP}$	400	mA
Reverse Voltage	$V_R$	5	V
Power Dissipation	$P_D$	300	mW
Electrostatic discharge	ESD	400	V
Operation Temperature	$T_{opr}$	-25~+80	°C
Storage Temperature	$T_{stg}$	-40~+80	°C
Lead Soldering Temperature*	$T_{sol}$	Max. 230°C for 5sec Max.	

\* $I_{FP}$  Conditions: Pulse Width  $\leq 10$ msec duty  $\leq 1/10$

\* $T_{sol}$  Conditions: 3mm from the base of the epoxy bulb

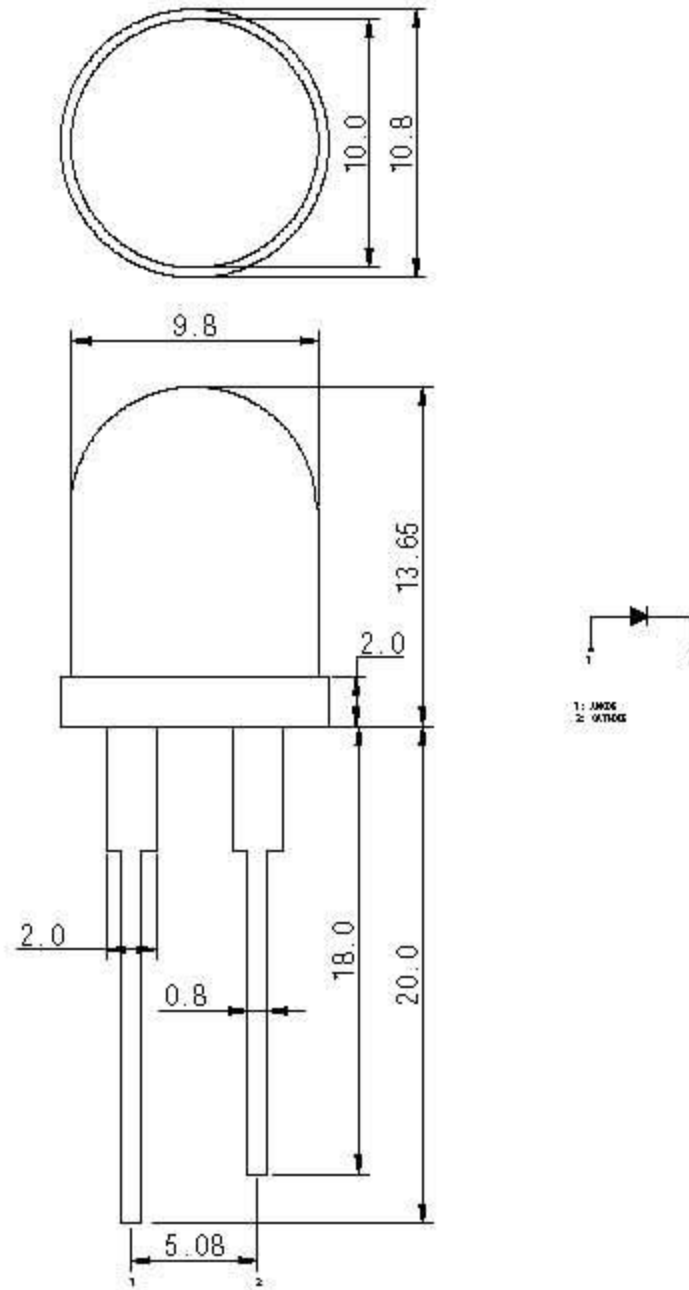
### ■ Typical Optical/ Electrical Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	$V_F$	$I_F=80$ mA	3.0	3.4	3.8	V
Reverse Current	$I_R$	$V_r=5$ V	--	--	10	uA
50% Power Angle	$2\theta_{1/2}$	$I_F=80$ mA	--	35	--	deg
Luminous Intensity	$I_V$	$I_F=80$ mA	8500	12000	--	mcd
Recommend Forward Current	$I_F(\text{rec})$	--	--	80	--	mA

Notes:

1. Absolute maximum ratings  $T_a=25$ °C.
2. Tolerance of measurement of forward voltage  $\pm 0.1$ V.
3. Tolerance of measurement of peak Wavelength  $\pm 2.0$ nm.
4. Tolerance of measurement of luminous intensity  $\pm 15$ %.

■ Package Dimensions And Materials



Chip		Lens Color
Material	Emitting Color	
GaN/SiC	WHITE	Water clear

Notes:

1. All dimension units are millimeters.
2. All dimension tolerance is  $\pm 0.2\text{mm}$  unless otherwise noted.
3. An epoxy meniscus may extend about 1.5mm down the leads.
4. Burr around bottom of epoxy may be 0.5mm max..

## ■ Reliability Performance

### 1. Test Items And Result

Test Classification	Test Item	Test Conditions	Test Duration	Sample Size	AC/RE
Life Test	Room Temperature DC Operating Life Test	Ta=25°C±5°C, IF=80mA	1000 hrs	30pcs	0/1
Environment Test	Thermal Shock Test	-10°C±5°C↔+100°C±5°C 5min. 10sec. 5min.	50 cycles	30 pcs	0/1
	Temperature Cycle Test	-40°C±5°C↔+85°C±5°C 30min. 5min. 30min.	50 cycles	30 pcs	0/1
	High Temperature & High Humidity Test	Ta=85°C±5°C RH =85%±0.5 %RH	1000 hrs	30 pcs	0/1
	High Temperature Storage	Ta=100°C±5°C	1000 hrs	30 pcs	0/1
	Low Temperature Storage	Ta=-55°C±5°C	1000 hrs	30 pcs	0/1
Mechanical Test	Resistance to Soldering Heat	Ta=230°C±5°C	5sec.	30 pcs	0/1
	Lead Integrity	Load 2.5N(0.25kgf) 0° ~ 90° ~0°	3times	30 pcs	0/1

### 2. Criteria for Judging The Damage

Item	Symbol	Test Conditions	Criteria for Judgment	
			Min.	Max.
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =80mA		U.S.L.*1.2
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V		U.S.L.*2.2
Luminous Intensity	I <sub>v</sub>	I <sub>F</sub> =80mA	L.S.L.**×0.7	

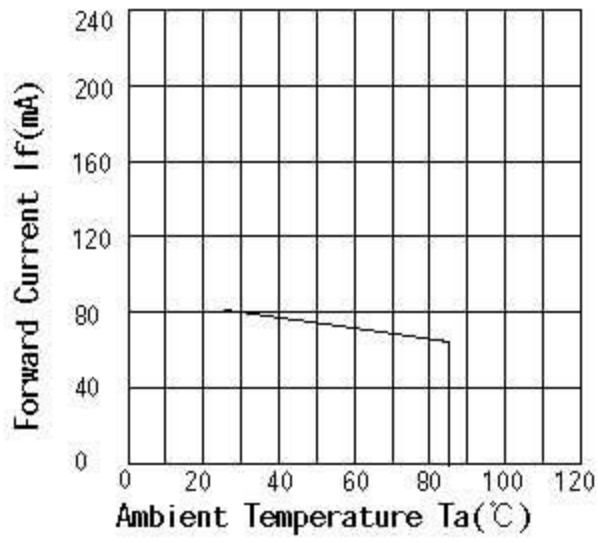
U.S.L.\* : Upper Standard Level

L.S.L.\*\* : Lower Standard Level

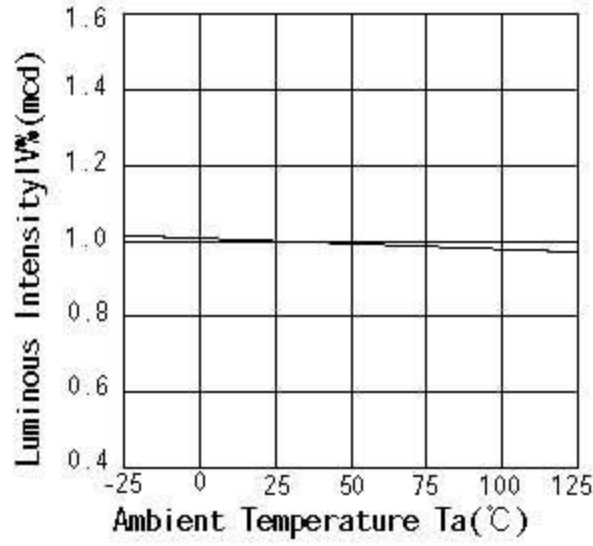
■ Typical Optical/Electrical Characteristics Curves

( $T_a=25^\circ\text{C}$  Unless Otherwise Noted )

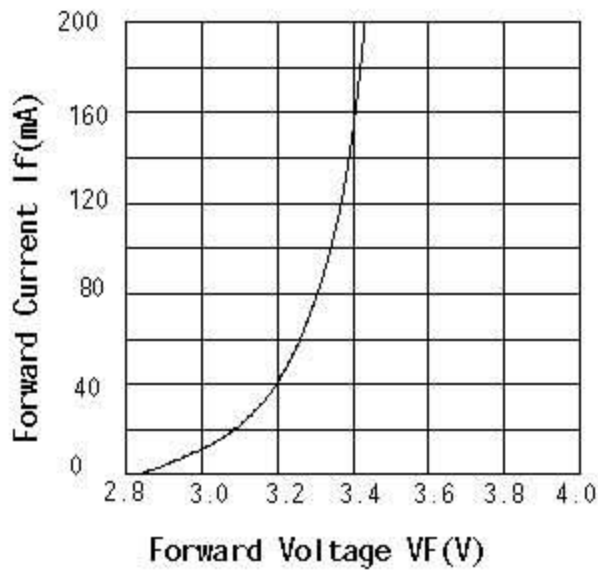
Forward Current vs. Ambient Temperature



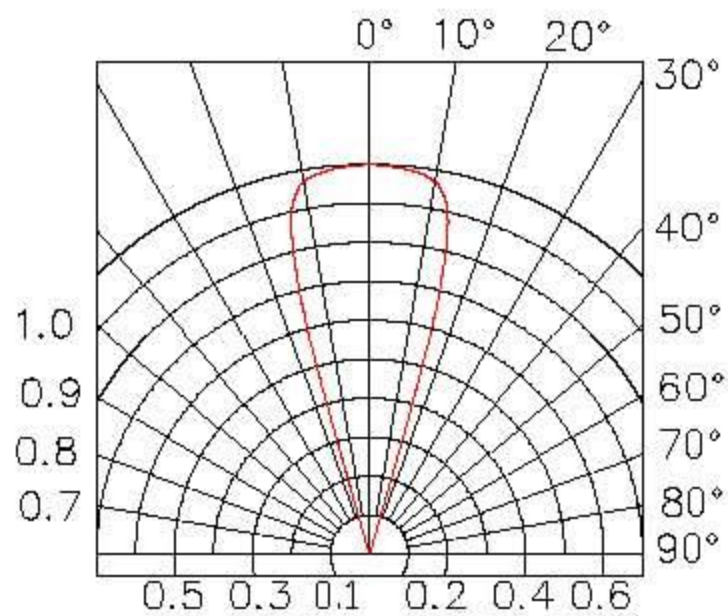
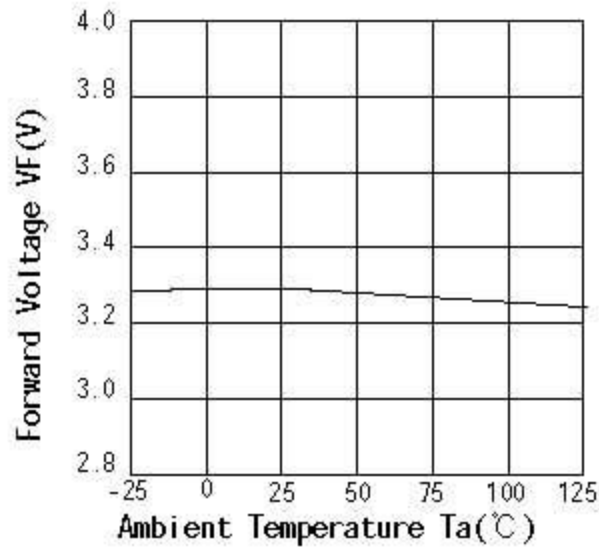
Relative Intensity vs. Ambient Temperature



Forward Current vs. Forward Voltage



Forward Voltage vs. Ambient Temperature



**Chromaticity Coordinates Specifications for Bin Grading**

Bin	Chromaticity Coordinates				
<b>A<sub>1</sub>~A<sub>17</sub></b>	X	0.21	0.21	0.47	0.47
	y	0.33	0.35	0.44	0.46
<b>B<sub>1</sub>~B<sub>17</sub></b>	X	0.21	0.21	0.47	0.47
	y	0.31	0.33	0.42	0.44
<b>C<sub>1</sub>~C<sub>17</sub></b>	X	0.21	0.21	0.47	0.47
	y	0.29	0.31	0.40	0.42
<b>D<sub>1</sub>~D<sub>17</sub></b>	X	0.21	0.21	0.47	0.47
	y	0.27	0.29	0.38	0.40
<b>E<sub>1</sub>~E<sub>17</sub></b>	X	0.21	0.21	0.47	0.47
	y	0.25	0.27	0.36	0.38
<b>F<sub>1</sub>~F<sub>17</sub></b>	X	0.21	0.21	0.47	0.47
	y	0.23	0.25	0.34	0.36
<b>G<sub>1</sub>~G<sub>17</sub></b>	X	0.21	0.21	0.47	0.47
	y	0.21	0.23	0.32	0.34
Change Area Coordinate Quotient			$X \pm 0.02$	$y \pm 0.02$	

